

# Grounding and Bonding— Part I. General

## PART I. GENERAL

**250.1 Scope.** Article 250 contains the following grounding and bonding requirements:

- (1) What systems and equipment are required to be grounded
- (3) Location of grounding connections
- (4) Types of electrodes and sizes of grounding and bonding conductors
- (5) Methods of grounding and bonding

### 250.2 Definitions.

**Bonding Jumper, System.** The conductor, screw, or strap that bonds the metal parts of a separately derived system to the system neutral point according to 250.30(A)(1). **Figure 250-1**

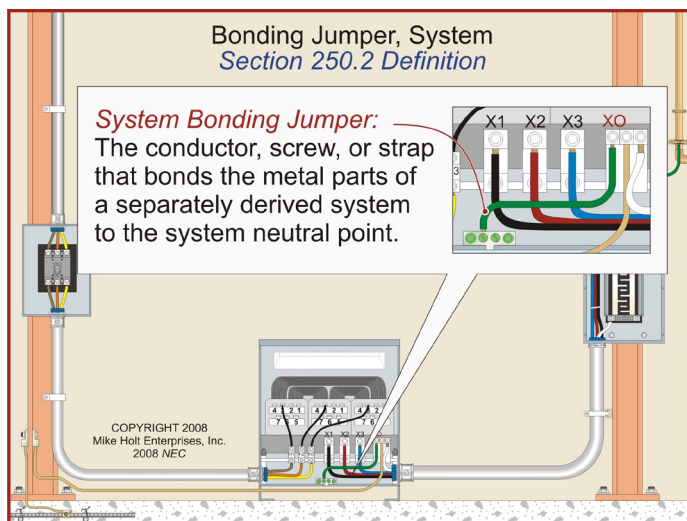


Figure 250-1

**Author's Comment:** The system bonding jumper provides a low-impedance fault current path to the power supply to facilitate the clearing of a ground fault by opening the circuit overcurrent device. For more information, see 250.4(A)(5), 250.28, and 250.30(A)(1).

**Effective Ground-Fault Current Path.** An intentionally constructed low-impedance conductive path designed to carry fault current from the point of a ground fault on a wiring system to the electrical supply source. **Figure 250-2**

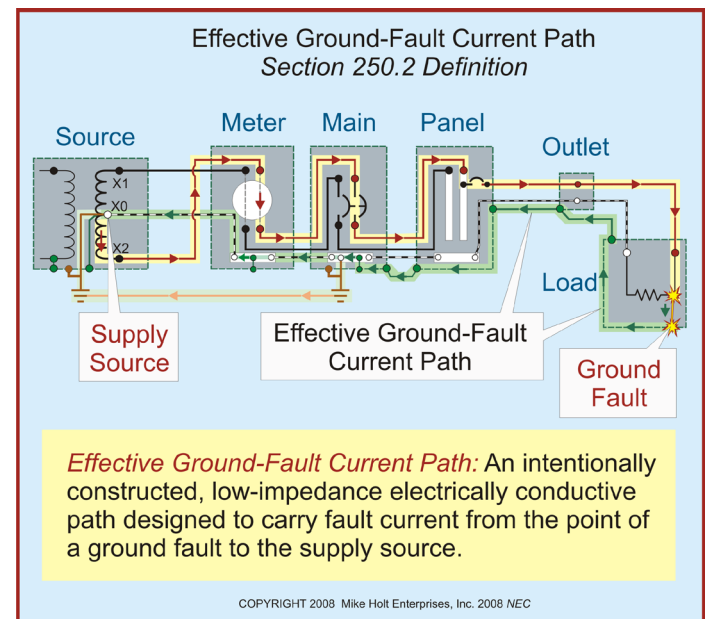


Figure 250-2

The effective ground-fault current path is intended to help remove dangerous voltage from a ground fault by opening the circuit overcurrent device. **Figure 250-3**

**Ground Fault.** An unintentional connection between an ungrounded conductor and the metal parts of enclosures, raceways, or equipment. **Figure 250-4**